



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-11-21
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC6H065B-TR	7ZDP*3D101T6	A	3068	2017-11-21
Amount	UoM	Unit type	ST ECOPACK Grade	
320.00	mg	Each	ECOPACK1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.10	Die back side metal - Leadframe metal	322
Lead	1.68	Soft solder	5241
Cobalt	0.46	Leadframe alloy	1444
Antimony trioxide	1.78	Molding compound	5563

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	7ZDP*3D101T6						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other Inorganic Materials	2.801	mg	supplier	die	Silicium carbide	409-21-2		2.734	mg	976080	8544	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.016	mg	5712	50	
				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	714	6	
				supplier	metallization	Silver (Ag)	7440-22-4		0.027	mg	9639	84	
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	357	3	
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	357	3	
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	714	6	
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.011	mg	3927	34	
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.007	mg	2499	22	
				supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	994601	512973	
Leadframe	Copper & its alloys	165.043	mg	supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	1999	1031	
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2799	1444	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.092	mg	557	288	
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	42	22	
				supplier	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	1.677	mg	955014	5241
				supplier	solder	Silver (Ag)	7440-22-4		0.044	mg	25057	138	
Soft solder	Solder	1.756	mg	supplier	solder	Tin (Sn)	7440-31-5		0.035	mg	19932	109	
				supplier	wire	Aluminium (Al)	7429-90-5		0.831	mg	1000000	2597	
				supplier	metalization	Phosphorus (P)	12185-10-3		0.007	mg	42	22	
Bonding wires	Other Inorganic Materials	0.831	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.831	mg	1000000	2597	
				supplier	metalization	Phosphorus (P)	12185-10-3		0.007	mg	42	22	
Encapsulation	Other Organic Materials	148.524	mg	supplier	mold compound	Silica, vitreous	60676-86-0		119.710	mg	805998	374094	
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		10.397	mg	70002	32491	
				supplier	mold compound	Phenol resin	9003-35-4		5.941	mg	40000	18566	
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		8.911	mg	59997	27847	
				supplier	mold compound	Antimony Trioxide	1309-64-4		1.782	mg	11998	5569	
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		1.040	mg	7002	3250	
				supplier	mold compound	Carbon black	1333-86-4		0.743	mg	5003	2322	
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266	
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266	